

**TSM 2301A****SOT-23****Pin Definition:**

1. Gate
2. Source
3. Drain

PRODUCT SUMMARY

V_{DS} (V)	R_{DS(on)}(mΩ)	I_D (A)
-20	130 @ V _{GS} = -4.5V	-2.8
	190 @ V _{GS} = -2.5V	-2.0

Features

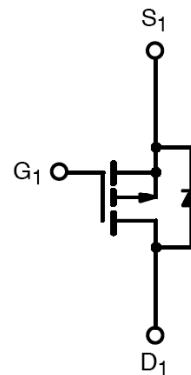
- Advance Trench Process Technology
- High Density Cell Design for Ultra Low On-resistance

Application

- Battery Management
- High Speed Switch

Ordering Information

Part No.	Package	Packing
TSM2301ACX RFG	SOT-23	3Kpcs / 7" Reel

Note: "G" denotes Halogen Free Product.**Block Diagram**

P-Channel MOSFET

Absolute Maximum Rating (T_A=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	±12	V
Continuous Drain Current	I _D	-2.8	A
Pulsed Drain Current	I _{DM}	-10	A
Continuous Source Current (Diode Conduction) ^{a,b}	I _S	-1	A
Maximum Power Dissipation	T _A =25°C	0.7	W
		0.45	
Operating Junction Temperature	T _J	+150	°C
Operating Junction and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Thermal Performance

Parameter	Symbol	Limit	Unit
Junction to Ambient Thermal Resistance (PCB mounted)	R _{θ_{JA}}	175	°C/W

Notes:

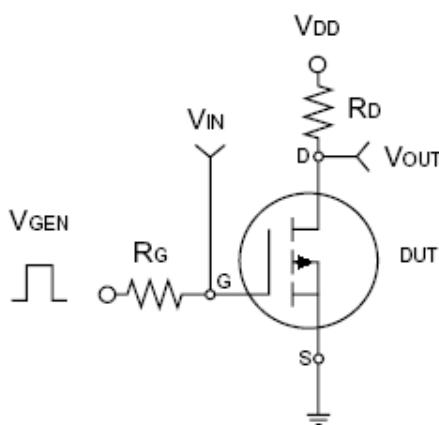
- a. Pulse width limited by the Maximum junction temperature
- b. Surface Mounted on a 1 in² pad of 2oz Cu, t ≤ 10 sec.

TSM 2301A**Electrical Specifications** ($T_a = 25^\circ\text{C}$ unless otherwise noted)

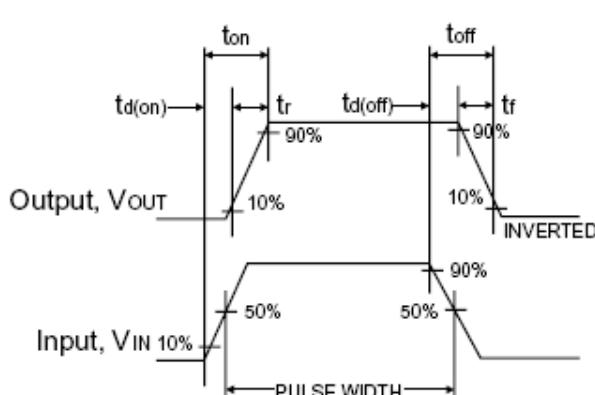
Parameter	Conditions	Symbol	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	$V_{GS} = 0\text{V}, I_D = 250\mu\text{A}$	BV_{DSS}	-20	--	--	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	$V_{GS(\text{TH})}$	-0.6	-0.7	-1	V
Gate Body Leakage	$V_{GS} = \pm 12\text{V}, V_{DS} = 0\text{V}$	I_{GSS}	--	--	± 100	nA
Zero Gate Voltage Drain Current	$V_{DS} = -20\text{V}, V_{GS} = 0\text{V}$	I_{DSS}	--	--	1.0	μA
Drain-Source On-State Resistance	$V_{GS} = -4.5\text{V}, I_D = -2.8\text{A}$	$R_{DS(\text{ON})}$	--	90	130	$\text{m}\Omega$
	$V_{GS} = -2.5\text{V}, I_D = -2.0\text{A}$		--	120	190	
Diode Forward Voltage	$I_S = -1\text{A}, V_{GS} = 0\text{V}$	V_{SD}	--	-0.7	-1.3	V
Dynamic^b						
Gate Resistance	$V_{GS} = V_{DS} = 0\text{V}, f = 1\text{MHz}$	R_g	--	7.5	--	Ω
Total Gate Charge	$V_{DS} = -6\text{V}, I_D = -2.8\text{A}, V_{GS} = -4.5\text{V}$	Q_g	--	7.2	--	nC
Gate-Source Charge		Q_{gs}	--	2.2	--	
Gate-Drain Charge		Q_{gd}	--	1.2	--	
Input Capacitance	$V_{DS} = -15\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	C_{iss}	--	480	--	pF
Output Capacitance		C_{oss}	--	460	--	
Reverse Transfer Capacitance		C_{rss}	--	10	--	
Switching^{b,c}						
Turn-On Delay Time	$V_{DD} = -6\text{V}, R_L = 6\Omega, V_{GEN} = -4.5\text{V}, R_G = 6\Omega$	$t_{d(on)}$	--	38	--	nS
Turn-On Rise Time		t_r	--	25	--	
Turn-Off Delay Time		$t_{d(off)}$	--	43	--	
Turn-Off Fall Time		t_f	--	5	--	

Notes:

- a. pulse test: $PW \leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- b. For DESIGN AID ONLY, not subject to production testing.
- c. Switching time is essentially independent of operating temperature.



Switching Test Circuit



Switching Waveforms